Fabricating and Studying van der Waals Heterostructures

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Why van der Waals heterostructures?

- Lab studies interaction between light, matter, and electric and magnetic fields
- Can stack layers of material to create van der Waals heterostructures to observe new physics
- High **degree of control** (electric, magnetic, mechanical) over sample
- Surface effects dominate
- Can study bilayer versions of ubiquitous systems such as p-n junctions



Geim & Grigorieva, Nature, 2013

- Hexagonal crystal lattice with chemical formula MX_2



- Hexagonal crystal lattice with chemical formula MX₂
- Semiconductor with gap between valence band and conduction band
- Monolayers have direct bandgap in visible spectrum → strong absorption and emission



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WSe ₂	
e-	MoSe ₂
↑	

WX,

MoX

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Studying interlayer excitons

- Applied electric field reveals quantumconfined Stark effect
- Want to measure exciton **decay time** and **energy emission spectrum** as a function of the applied electric field



Schaibley et al., Nature Reviews: Materials, 2016



Seeing the physics: device to data



Find materials Ensure quality

 \bullet

Characterize

Design device

• Stack pieces

- Make electrical contact
- Wire electrical contacts to cryostat

 Cool to T < 4K

- Collect data
- Discover interesting new physics?

Fabrication Process: Collecting Materials



Fabrication Process: Device Planning

Or, "measure twice, cut once"

Desired electrical control dictates stacking pattern

Need to know precise orientation and where to pick up each piece



Fabrication Process: Transfer





many degrees of freedom

Fabrication Process: Transfer

Melting down stamp covering assembled device onto chip



Fabrication Process: Evaporating Contacts





Fabrication Process: Evaporating Contacts





Fabrication Process: Evaporating Contacts



Chip with stacked device





Fabrication Process: Wire-bonding & Cooldown

Wiring electrical contact (gold) between device and mount



Completed device in cryostat



Data Collection: Experimental Schematic





What it means; where its going

- Discovering new physical phenomena
- Applications to photon energy harvesting, information technology and perhaps more
- Assembly and mass-production are difficult
- Not all the observed effects are understood, and not all the predicted effects have been observed
- "Publish or perish" → "Device or doom"

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References

[1] A. K. Geim and I. V. Grigorieva, "Van der Waals Heterostructures," Nature, vol. 499, pp. 419 – 425, 2013.

[2] J. R. Schaibley, H. Yu, G. Clark, P. Rivera, J. S. Ross, K. L. Syler, W. Yao and X. Xu, "Valleytronics in 2D materials," *Nature Reviews: Materials*, vol. 1, pp. 1-15, 2016.

[3] X. Xu, W. Yao, D. Xiao and T. F. Heinz, "Spin and pseudospins in layered transition metal dichalcogenides," *Nature Physics*, vol. 10, pp. 343-350, 2014.

Fabrication Process: Transfer



Lifting piece off of chip



Melting down stamp covering assembled device onto chip

Full transfer station

